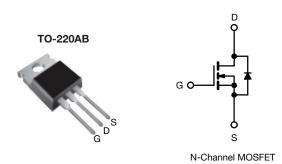
www.vishay.com

Vishay Siliconix

# **EF Series Power MOSFET With Fast Body Diode**



PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max.	850			
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.305		
Q <sub>g</sub> max. (nC)	54			
Q <sub>gs</sub> (nC)	7			
Q <sub>gd</sub> (nC)	15			
Configuration	Single			

### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)

 Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912">www.vishav.com/doc?99912</a>



#### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free and halogen-free	SIHP15N80AEF-GE3		

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V <sub>DS</sub>	800	.,	
Gate-source voltage			$V_{GS}$	± 30	V	
Continuous drain current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	$T_C = 25 \degree C$ $T_C = 100 \degree C$	- I <sub>D</sub>	13		
	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		8	Α	
Pulsed drain current a			I <sub>DM</sub>	28		
Linear derating factor				1.25	W/°C	
Single pulse avalanche energy b			E <sub>AS</sub>	28	mJ	
Maximum power dissipation			$P_{D}$	156	W	
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-source voltage slope $T_J = 125 ^{\circ}\text{C}$		dv/dt	100	\//		
Reverse diode dv/dt d			15	V/ns		
Soldering recommendations (peak temperatur	re) c	For 10 s		260	°C	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 140 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = 1.4 A
- c. 1.6 mm from case
- d.  $I_{SD} \le I_D$ , di/dt = 100 A/ $\mu$ s, starting  $T_J = 25$  °C



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R <sub>thJA</sub>	=	62	°C/W	
Maximum junction-to-case (drain)	$R_{thJC}$	-	0.8	C/VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static				L			
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		800	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I <sub>D</sub> = 1 mA		-	0.7	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_D = 250 \mu A$		-	4	V
Coto come lockers	I <sub>GSS</sub>	V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Gate-source leakage		,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zeve gete veltege dvein euwent		V <sub>DS</sub> =	640 V, V <sub>GS</sub> = 0 V	-	-	1	μA
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 640 V	, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	2	mA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 6.5 A	-	0.305	0.350	Ω
Forward transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> =	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 6.5 A		7.0	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V,		-	1128	-	pF
Output capacitance	C <sub>oss</sub>	,	V <sub>DS</sub> = 0 V,		41	-	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1 MHz		-	5	-	
Effective output capacitance, energy related	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V		-	34	-	
Effective output capacitance, time related	C <sub>o(tr)</sub>			-	209	-	
Total gate charge	Qg			-	36	54	
Gate-source charge	$Q_{gs}$	$V_{GS} = 10 \text{ V}$	$V_{GS} = 10 \text{ V}$ $I_D = 6.5 \text{ A}, V_{DS} = 640 \text{ V}$		7	-	nC
Gate-drain charge	$Q_gd$			-	15	-	<u>l                                    </u>
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 640 V, I <sub>D</sub> = 6.5 A,		-	14	28	- ns
Rise time	t <sub>r</sub>			-	14	28	
Turn-off delay time	t <sub>d(off)</sub>	V <sub>GS</sub> =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		18	36	
Fall time	t <sub>f</sub>			-	43	86	
Gate input resistance	$R_g$	f = 1 MHz, open drain		0.2	0.5	1.1	Ω
<b>Drain-Source Body Diode Characteristic</b>	es						
Continuous source-drain diode current	I <sub>S</sub>	showing the	MOSFET symbol showing the		-	13	
Pulsed diode forward current	I <sub>SM</sub>	integral reverse p - n junction diode		-	-	28	- A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 6.5 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>			-	104	208	ns
Reverse recovery charge	Q <sub>rr</sub>	$T_J = 25$ °C, $I_F = I_S = 6.5$ A, di/dt = 100 A/ $\mu$ s, $V_R = 25$ V		-	0.4	0.8	μC
Reverse recovery current	I <sub>RRM</sub>			_	8	-	Α



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

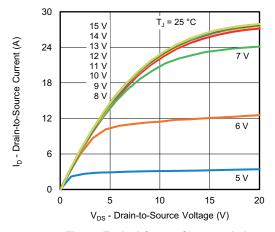


Fig. 1 - Typical Output Characteristics

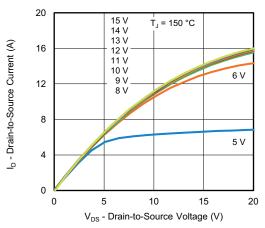


Fig. 2 - Typical Output Characteristics

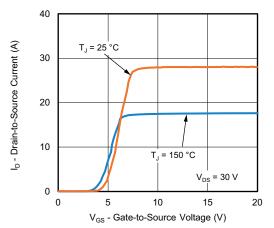


Fig. 3 - Typical Transfer Characteristics

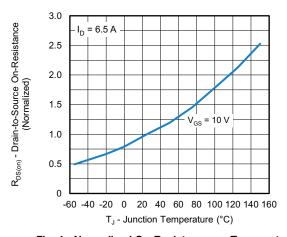


Fig. 4 - Normalized On-Resistance vs. Temperature

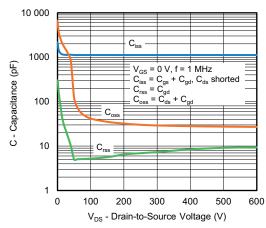


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

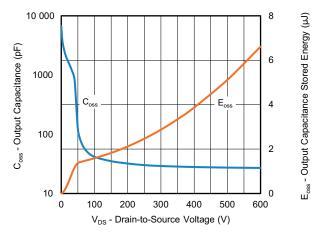


Fig. 6 - Coss and Eoss vs. VDS



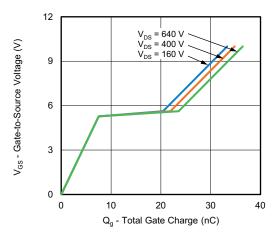


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

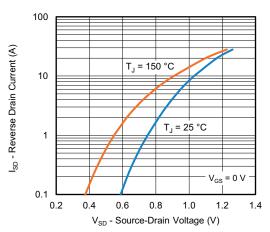


Fig. 8 - Typical Source-Drain Diode Forward Voltage

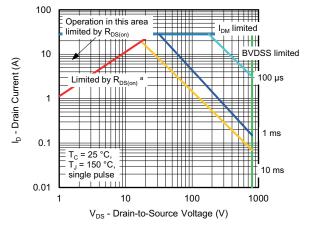


Fig. 9 - Maximum Safe Operating Area

### Note

a.  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

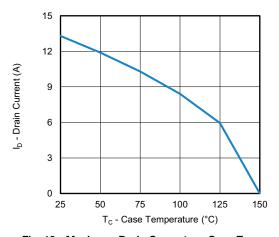


Fig. 10 - Maximum Drain Current vs. Case Temperature

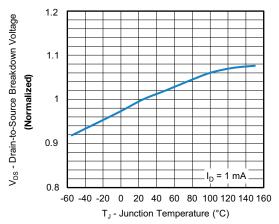


Fig. 11 - Temperature vs. Drain-to-Source Voltage



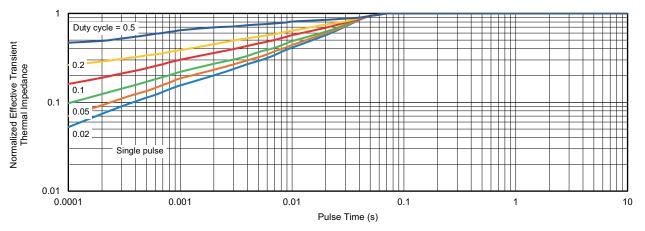


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

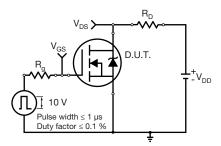


Fig. 13 - Switching Time Test Circuit

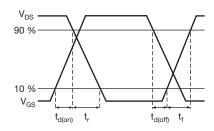


Fig. 14 - Switching Time Waveforms

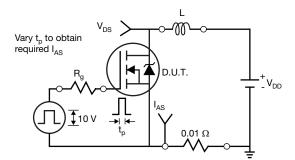


Fig. 15 - Unclamped Inductive Test Circuit

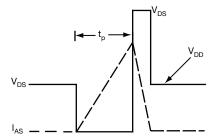


Fig. 16 - Unclamped Inductive Waveforms

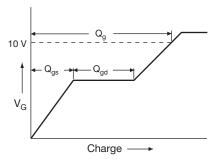


Fig. 17 - Basic Gate Charge Waveform

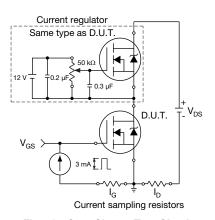
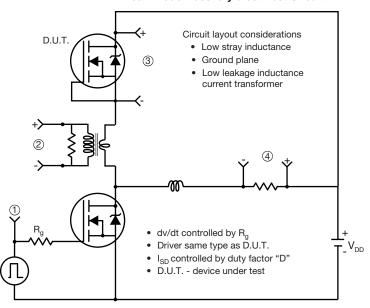


Fig. 18 - Gate Charge Test Circuit



### Peak Diode Recovery dv/dt Test Circuit



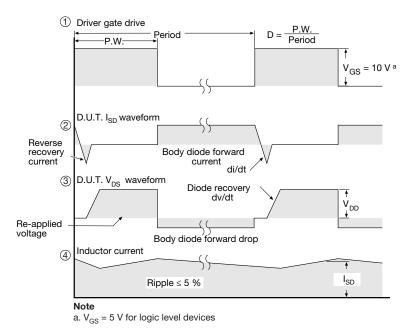


Fig. 19 - For N-Channel

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